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Part Number: [0739425000](#)
Status: **Active**
Overview: [HDM® Backplane Connector System](#)
Description: HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Open End, 144 Circuits

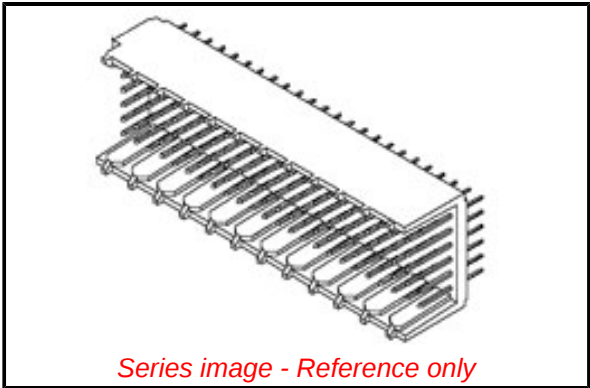
Documents:
[3D Model](#) [Packaging Specification PK-70873-0818 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification
CSA LR19980
UL E29179

General
Product Family Backplane Connectors
Series [73942](#)
Application Backplane
Comments Solder Tail
Component Type PCB Header
Overview [HDM® Backplane Connector System](#)
Product Name HDM®
UPC 800753935020

Physical
Circuits (Loaded) 144
Circuits (maximum) 144
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Net Weight 6.273/g
Number of Columns 24
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 3.00mm
PCB Locator No
PCB Retention None
PCB Thickness - Recommended 2.50mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 2.540µm
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55°C to +105°C
Termination Interface: Style Through Hole

Electrical
Current - Maximum per Contact 1.0A



Series image - Reference only

EU ELV
Not Relevant

EU RoHS **China RoHS**
Compliant
REACH SVHC
Not Contained Per
-ED/01/2017 (12
January 2017)
Halogen-Free
Status
Low-Halogen
Need more information on product environmental compliance?

Email productcompliance@molex.com
Please visit the [Contact Us](#) section for any non-product compliance questions.

China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series
[73942](#) Series

Mates With
[73632](#) HDM+® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Data Rate	1.0 Gbps
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	040
Lead-freeProcess Capability	SMC&WAVE
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Sales Drawing	SD-73942-001

Note: HDM, HDM+, VHDM, VHDM-HSD and GbX are trademarks or registered trademarks of Amphenol TCS.

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